

ABSTRACT OF THE DISCLOSURE

Embodiments of the invention provide methods for mounting and dicing a double bumped wafer. For one embodiment, the thickness of the adhesive layer of a dicing tape is greater than the height of the bumps to which it is applied, such that the adhesive layer conforms to the bumps and distributes the pressure of a mounting roller more evenly. For one embodiment, the dicing tape has an adhesive layer approximately twice the thickness of the wafer bump to which it is applied. For one embodiment, a radiation sensitive adhesive is used that has a pre-radiation adhesive strength of approximately 200 grams/25 mm² and a post-radiation adhesive strength of approximately 2 grams/25 mm². For one embodiment, a dual blade dicing process is employed that cuts into only a portion of the adhesive layer of the dicing tape in order to reduce adhesive blade loading.